

JL7083H Datasheet

Zhuhai Jieli Technology Co.,LTD

Version 1.0

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Revision History

Date	Revision	Description
2025.08.19	V1.0	Initial Release



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JL7083H Features

SYSTEM

- Dual Core 32bit DSP 192MHz
- With IEEE754 Single precision FPU
- Support FFT/MATRIX/MATH
- Support NPU
- 2 x I-cache and D-cache
- Support SDTAP/EMU
- On-chip SRAM 384kbyte
- Support MMU
- Support MPU
- Built-In Flash
- 24MHz crystal oscillator
- Internal RC oscillator, PLL

DSP Audio Processing

- SBC/AAC/LDAC/LHDC/LC3/CVSD/mSBC codec
- CVSD/mSBC voice codec for BT phone
- PLC for voice processing
- Single/Multi MIC ENC
- Multi-band DRC
- Multi-band EQ
- Support spatial sound
- Support assistive listening
- Support Hi-Res Audio

ANC

- Wide band digital adaptive ANC
- Support hybrid/feedforward/feedback
- Support wind noise detection
- Support wide area tap
- Support Speak-to-Chat
- Support tip fit test & wear detection
- Input-to-output latency < 8us

Audio

- 1 x 24bit DAC
 - ❖ SNR 119dB
 - ❖ Noise 1uVrms
 - ❖ Supports differential mode
 - ❖ Sampling rate 8~192kHz
- 4 x 24bit ADC

- ❖ SNR 106dB
- ❖ Sampling rate 8~192kHz
- ❖ Support ultra-low power mode
- I²S/TDM/PDM AUDIO Master/Slave interface

Bluetooth

- Dual-mode BT6.0 with LE Audio (DN Q332415)
- Support AoA/AoD
- Support LE audio BIS/CIS
- Support long range BLE
- Maximum transmitting power 13dBm
- Receiver sensitivity
 - ❖ -98dBm @BR
 - ❖ -98.5dBm @EDR $\pi/4$ DQPSK
 - ❖ -92dBm @EDR 8DPSK

Peripherals

- 1 x Full speed USB
- 1 x SD host controller
- 6 x Multi-function 32bit timer
- 3 x UART interface
- 1 x I²C Master/Slave interface
- 3 x SPI Master/Slave interface
- 1 x QDEC
- 4 x MCPWM
- 2 x Light strip controller
- 1 x 10bit ADC(10 Channels)
- 18 x GPIO Support function remapping
- 5 x LP_Touch with low power wake up

PMU

- Integrated battery charger up to 220mA
- 3 x Buck DC-DC converter
- Support temperature sensor
- VPWR range 4.5V to 5.5V
- VBAT range 2.7V to 4.5V
- IOVDD range 2.7V to 3.6V

Packages

- QFN42(4mm*5mm)

Temperature

- Operating temperature
TC = -20℃ to +85℃(standard range)
TC = -40℃ to +105℃(extended range)
- Storage temperature -65℃ to +150℃

Applications

- Adaptive ANC TWS
- Bluetooth audio device

1 Block Diagram

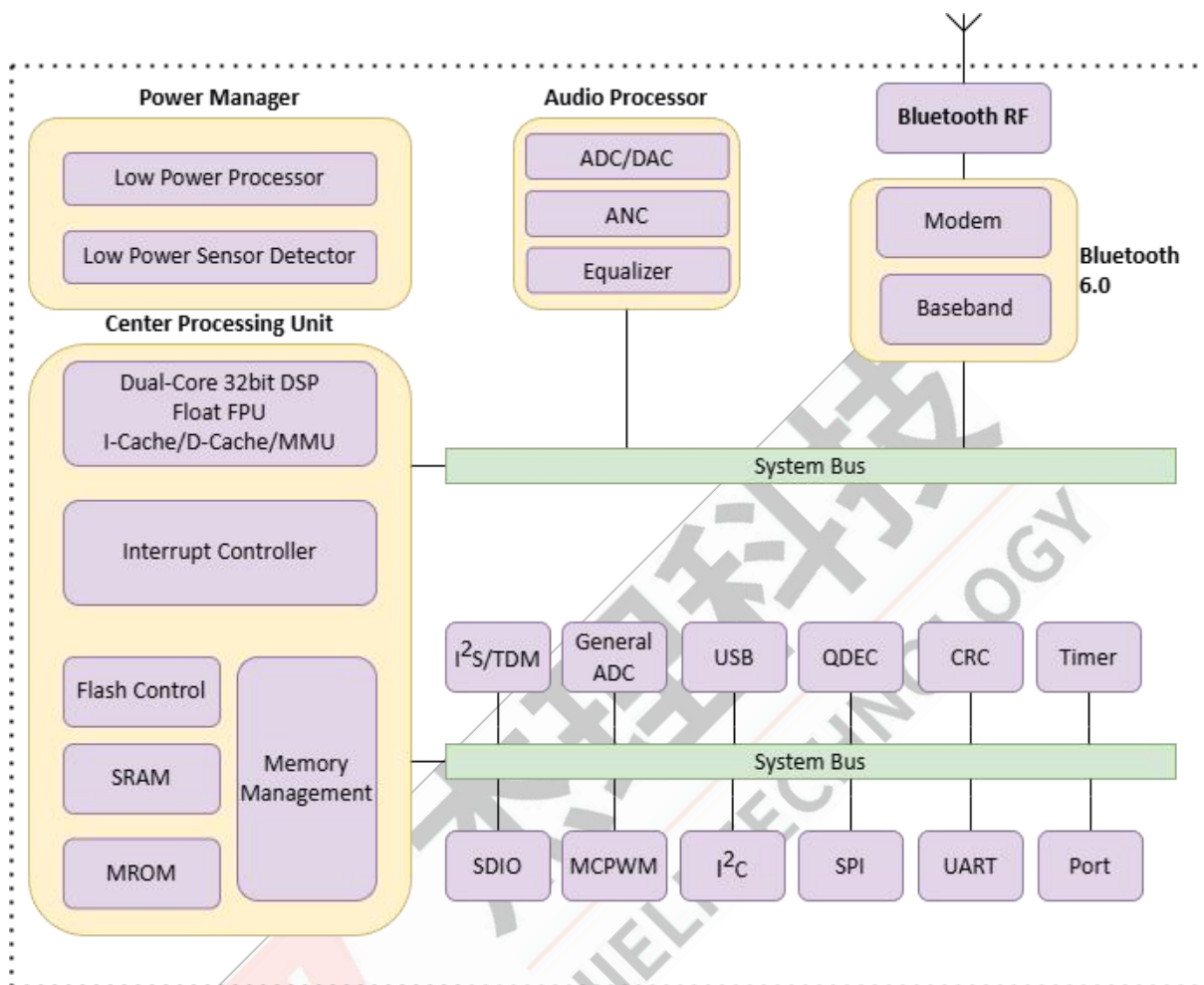


Figure 1-1 JL7083H Block Diagram

2 Pin Definition

2.1 Pin Assignment

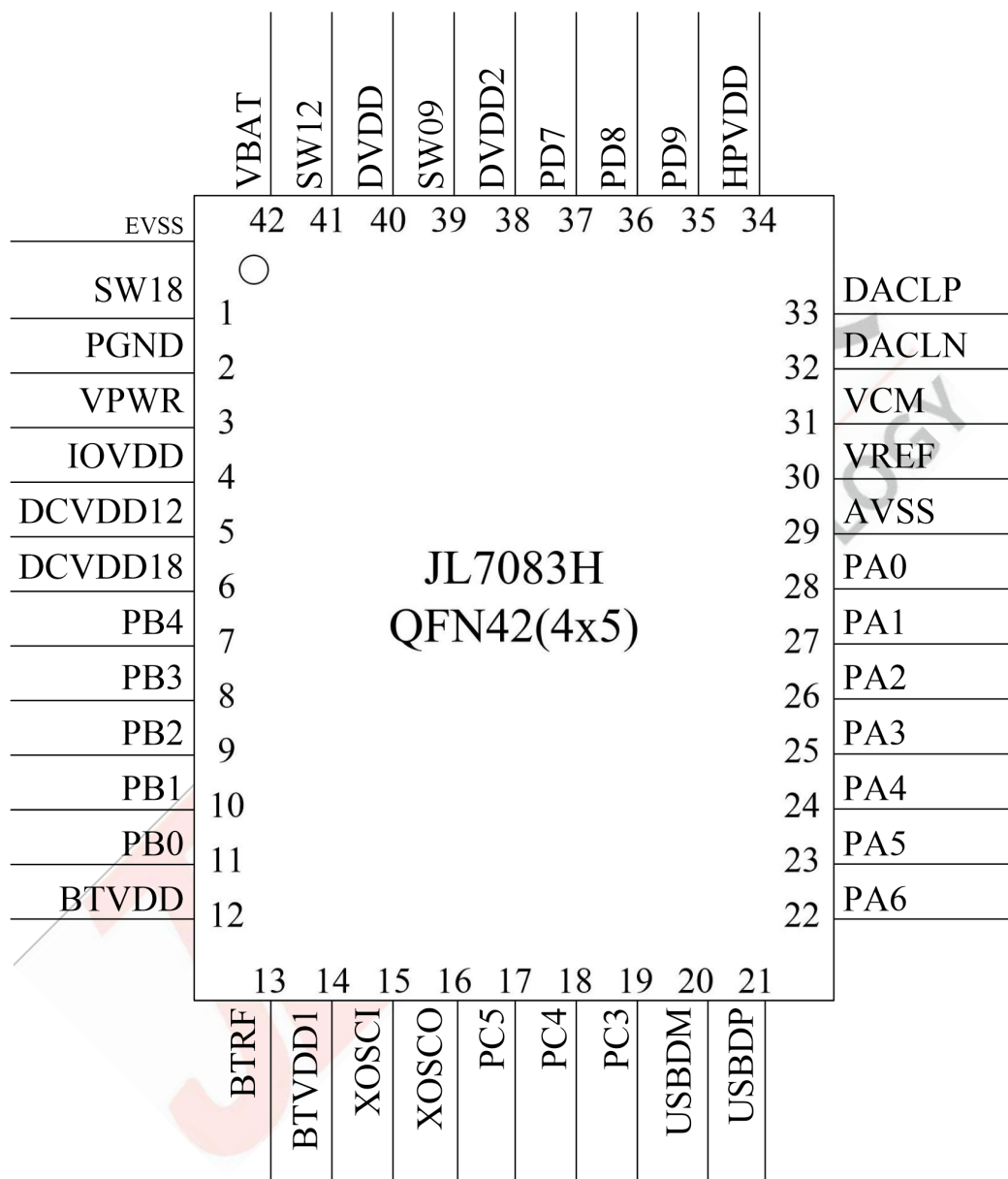


Figure 2-1 JL7083H Pin Assignment

2.2 Pin Description

Table 2-2-1 JL7083H Pin Description

Pin No.	Name	Type	IO Initial State	Description
1	SW18	P	--	1.8V Buck DCDC Switch Port
2	PGND	G	--	Ground of Buck DC-DC converter
3	VPWR	P	Z	Charge Power Input
4	IOVDD	P	--	3.0V Power
5	DCVDD12	P	--	1.2V Power
6	DCVDD18	P	--	1.8V Power
7	PB4	I/O	Z	ADC5(ADC Input Channel 5) LP_TOUCH4(TOUCH_CH4)
8	PB3	I/O	Z	ADC4(ADC Input Channel 4) LP_TOUCH3(TOUCH_CH3)
9	PB2	I/O	Z	ADC3(ADC Input Channel 3) LP_TOUCH2(TOUCH_CH2)
10	PB1	I/O	10kΩ Pull-up	ADC2(ADC Input Channel 2) LP_TOUCH1(TOUCH_CH1) Hold down 0 to reset
11	PB0	I/O	Z	ADC1(ADC Input Channel 1) LP_TOUCH0(TOUCH_CH0) LVD(External Low Voltage Detection Input)
12	BTVDD	P	--	BT Power
13	BTRF	RF	--	Bluetooth RF Antenna
14	BTVDD1	P	--	BT Power
15	XOSCI	I	--	Crystal Oscillator Input
16	XOSCO	O	--	Crystal Oscillator Output
17	PC5	I/O	Z	ADC10(ADC Input Channel 10)
18	PC4	I/O	Z	ADC9(ADC Input Channel 9)
19	PC3	I/O	Z	ADC8(ADC Input Channel 8)
20	USBDM	I/O	15kΩ Pull-down	USB Negative Data ADC15(ADC Input Channel 15)
21	USBDP	I/O	15kΩ Pull-down	USB Positive Data ADC14(ADC Input Channel 14)
22	PA6	I/O	Z	AIN_AN0(Audio ADC Negative Input) LPAIN_N1(Low Power ADC Negative Input)
23	PA5	I/O	Z	AIN_AP0(Audio ADC Positive Input) LPAIN_P1(Low Power ADC Positive Input)

Pin No.	Name	Type	IO Initial State	Description
24	PA4	I/O	Z	MICBIASA(MIC Bias Output) LPAIN_N0(Low Power ADC Negative Input) AIN_BN1(Audio ADC Negative Input) AIN_AN1(Audio ADC Negative Input)
25	PA3	I/O	Z	MICBIASB(MIC Bias Output) LPAIN_P0(Low Power ADC Positive Input) AIN_BP1(Audio ADC Positive Input) AIN_AP1(Audio ADC Positive Input)
26	PA2	I/O	Z	AIN_BN0(ADC Negative Input) AIN_DN1(ADC Negative Input)
27	PA1	I/O	Z	AIN_BP0(Audio ADC Positive Input) AIN_DP1(Audio ADC Positive Input)
28	PA0	I/O	Z	LPMICBIASA(MIC Bias Output)
29	AVSS	G	--	Audio Ground
30	VREF	P	--	Audio Power
31	VCM	P	--	Audio reference voltage
32	DACLN	O	--	Left Channel DAC Negative Output
33	DACL P	O	--	Left Channel DAC Positive Output
34	HPVDD	P	--	Audio Power
35	PD9	I/O	Z	ADC13(ADC Input Channel 13) MICLDO(MIC Bias LDO Output) MICBIASC(MIC Bias Output)
36	PD8	I/O	Z	AIN_CN0(Audio ADC Negative Input) LPAIN_N2(Low Power ADC Negative Input)
37	PD7	I/O	Z	AIN_CP0(Audio ADC Positive Input) LPAIN_P2(Low Power ADC Positive Input)
38	DVDD2	P	--	Digital Power
39	SW09	P	--	0.9V Buck DCDC Switch Port
40	DVDD	P	--	Digital Power
41	SW12	P	--	1.2V Buck DCDC Switch Port
42	VBAT	P	--	Battery Input

Note

- 1.IO initial state abbreviations Z--High resistance, H--High level, L--Low level, X--May be changed during power on.
- 2.Timer, MCPWM, QDEC, UART, LEDC, I²C, I²S, SPI and SD functions can be remapped to any I/O.

Table 2-2-2 Pin types description

Pin Type	Description	Pin Type	Description
P	Power	I/O	Input or Output
G	Ground	I	Input
RF	RF antenna	O	Output

3 Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3-1 Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
Topt	Operating temperature	-20	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	4.5	V
VPWR		-0.3	6.0	V
IOVDD		-0.3	3.6	V
DCVDD12		-0.3	1.3	V
DCVDD18		-0.3	2.0	V
BTVDD		-0.3	2.0	V
BTVDD1		-0.3	1.3	V
VREF		-0.3	1.0	V
HPVDD		-0.3	2.0	V
GPIO	Input voltage of GPIO	-0.3	3.6	V

Note

1.Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device.

3.2 ESD Ratings

Table 3-2 ESD Ratings

Parameter	Typ	Test pin	Reference standard
Human Body Mode	±4kV	All pins	JEDEC EIA/JESD22-A114
Machine Mode	±200V	All pins	JEDEC EIA/JESD22-A115
Charge Device Model	±1kV	All pins	ANSI/ESDA/JEDEC JS-002-2022

3.3 PMU Characteristics

Table 3-3 PMU Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VBAT	Power supply	--	2.7	3.7	4.5	V
VPWR	Power supply	--	4.5	5.0	5.5	V
Operating mode						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IOVDD	Voltage output	--	--	3.0	--	V
	Loading current	IOVDD=3.0V@VBAT = 3.7V	--	--	200	mA
DCVDD12	Voltage output	--	--	1.2	--	V
	Loading current	DCVDD12=1.2V@VBAT = 3.7V	--	--	150	mA
DCVDD18	Voltage output	--	--	1.8	--	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	Loading current	DCVDD18=1.8V@VBAT = 3.7V	--	--	180	mA
Low Power mode						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IOVDD	Loading current	IOVDD=3.0V@VBAT = 3.7V	--	--	20	mA

3.4 Battery Charge

Table 3-4 Charger Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VPWR	Charge Input Voltage	VBAT+0.1V	5.0	5.5	V
CV	CV Mode Voltage Accuracy	4.175	4.2	4.225	V
		4.325	4.35	4.375	V
CC	CC Mode Current	20	--	220	mA
I _{end}	End Of Charge Current	2	--	22	mA
V _{Trickl}	Trickle Charge Voltage	--	3.0	--	V

3.5 IO Characteristics

Table 3-5 IO Characteristics

Input Characteristics						
Symbol	Parameter	Conditions	IO	Min	Max	Unit
V _{IL}	Low-Level Input Voltage	IOVDD = 3.0V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9 USBDP USBDM VPWR	-0.3	1.4	V
V _{IH}	High-Level Input Voltage	IOVDD = 3.0V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9 USBDP USBDM	1.7	3.3	V
		IOVDD = 3.0V	VPWR	1.7	5.5	V
Output Characteristics						
Symbol	Parameter	Conditions	IO	Typ		Unit

I _{OL}	Output Current	IOVDD = 3.0V Voutput = 0.3V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9	2(HD=0) 8(HD=1) 26(HD=2) 50(HD=3)	mA
		IOVDD = 3.0V Voutput = 0.3V	USBDP USBDM	8	mA
		IOVDD = 3.0V Voutput = 0.3V	VPWR	2	mA
I _{OH}	Output Current	IOVDD = 3.0V Voutput = 2.7V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9	2(HD=0) 8(HD=1) 26(HD=2) 50(HD=3)	mA
		IOVDD = 3.0V Voutput = 2.7V	USBDP USBDM	8	mA
		IOVDD = 3.0V Voutput = 2.7V	VPWR	2	mA
Internal Resistance Characteristics					
Symbol	Parameter	Conditions	IO	Typ	Unit
R _{pu}	Pull-up Resistance	IOVDD = 3.0V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9 VPWR	10k(PU=1) 100k(PU=2) 1M(PU=3)	Ω
		IOVDD = 3.0V	USBDP	1.5k	Ω
		IOVDD = 3.0V	USBDM	180k	Ω
R _{pd}	Pull-down Resistance	IOVDD = 3.0V	PA0~PA6 PB0~PB4 PC3~PC5 PD7~PD9 VPWR	10k(PD=1) 100k(PD=2) 1M(PD=3)	Ω
		IOVDD = 3.0V	USBDP USBDM	15k	Ω

Note

1.Internal pull-up/pull-down resistance accuracy ±20%

3.6 Audio DAC Characteristics

Table 3-6-1 DAC Characteristics under HPVDD 1.8V

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Output Sample Rate	--	8	--	192	kHz
SNR ^①	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	119	--	dB
Dynamic Range	Differential Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	109	--	dB
THD+N	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=32Ω	--	-87	--	dB
Noise Floor	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	2.6	--	uVrms
Noise Floor with MUTE	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	1	--	uVrms
Max Output Power	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=16Ω THD+N<0.1%	--	30	50	mW

Note

1. ^①SNR is the ratio of output level with a 1kHz full-scale input to output level with MUTE on.

Table 3-6-2 DAC Characteristics under HPVDD 1.2V

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Output Sample Rate	--	8	--	192	kHz
SNR ^①	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz	--	117	--	dB

Parameter	Conditions	Min	Typ	Max	Unit
	B/W=20Hz~20kHz A-Weighted Load=10kΩ				
Dynamic Range	Differential Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	107	--	dB
THD+N	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=32Ω	--	-83	--	dB
Noise Floor	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	2.6	--	uVrms
Noise Floor with MUTE	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	1	--	uVrms
Max Output Power	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=16Ω THD+N<0.1%	--	20	TBC	mW

Note

1. ① SNR is the ratio of output level with a 1kHz full-scale input to output level with MUTE on.

3.7 Audio ADC Characteristics

Table 3-7 Audio ADC Characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Input Sample Rate	--	8	--	192	kHz
SNR	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	106	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	104	--	dB
Dynamic Range	Differential input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	106	--	dB
	Single-ended input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	104	--	dB
THD+N	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-90	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-90	--	dB
Analogue Gain		-6	--	21	dB
Max Input Level	Differential input Mode ADC gain=0dB	--	1	--	Vrms
	Single-ended input Mode ADC gain=0dB	--	0.5	--	Vrms

3.8 BT Characteristics

3.8.1 Transmitter

Table 3-8-1-1 Transmitter characteristics under BTVDD 1.8V

Parameter	Conditions	Min	Typ	Max	Unit
Maximum RF Transmit Power	BR	--	10	13	dBm
Maximum RF Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	10	--	dBm
Relative Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	-3	--	dB
Maximum RF Transmit Power	BLE-1Mbps	--	10	13	dBm
Maximum RF Transmit Power	BLE-2Mbps	--	10	13	dBm

Table 3-8-1-2 Transmitter characteristics under BTVDD 1.2V

Parameter	Conditions	Min	Typ	Max	Unit
Maximum RF Transmit Power	BR	--	8	10	dBm
Maximum RF Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	8	--	dBm
Relative Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	-3	--	dB
Maximum RF Transmit Power	BLE-1Mbps	--	8	10	dBm
Maximum RF Transmit Power	BLE-2Mbps	--	8	10	dBm

3.8.2 Receiver

Table 3-8-2 Receiver characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Sensitivity	BR	--	-98	--	dBm
	EDR $\pi/4$ DQPSK	--	-98.5	--	dBm
	EDR 8DPSK	--	-92	--	dBm
	BLE-1Mbps	--	-101	--	dBm
	BLE-2Mbps	--	-97.5	--	dBm
	BLE-S2	--	-104	--	dBm
	BLE-S8	--	-109	--	dBm

4 Package Information

4.1 QFN42_4×5mm

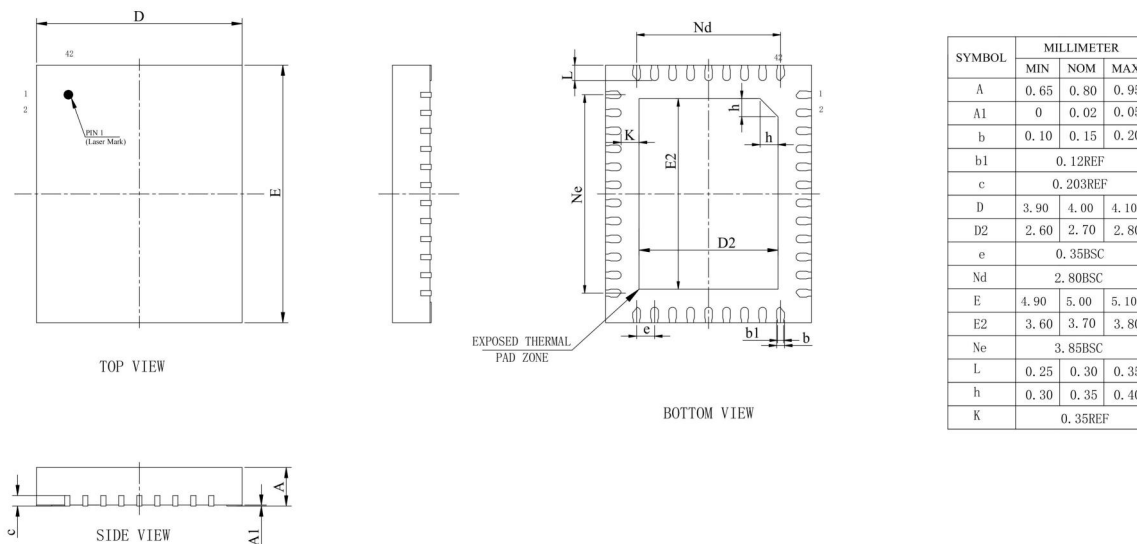


Figure 4-1 JL7083H Package

5 IC Marking Information

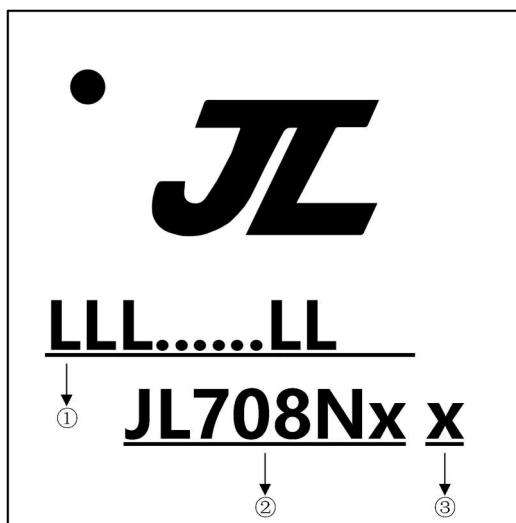


Figure 5-1 JL7083H Package Outline

- ① LLL.....LL: LOT No. , It contains 7 to 18 alphanumerics
- ② JL708Nx : Chip Model
- ③ x : Built-in flash size
 - 0 : No Flash Memory
 - 2 : 2Mbit Flash
 - 4 : 4Mbit Flash
 - 8 : 8Mbit Flash
 - 6 : 16Mbit Flash
 - 3 : 32Mbit Flash

6 Solder-Reflow Condition

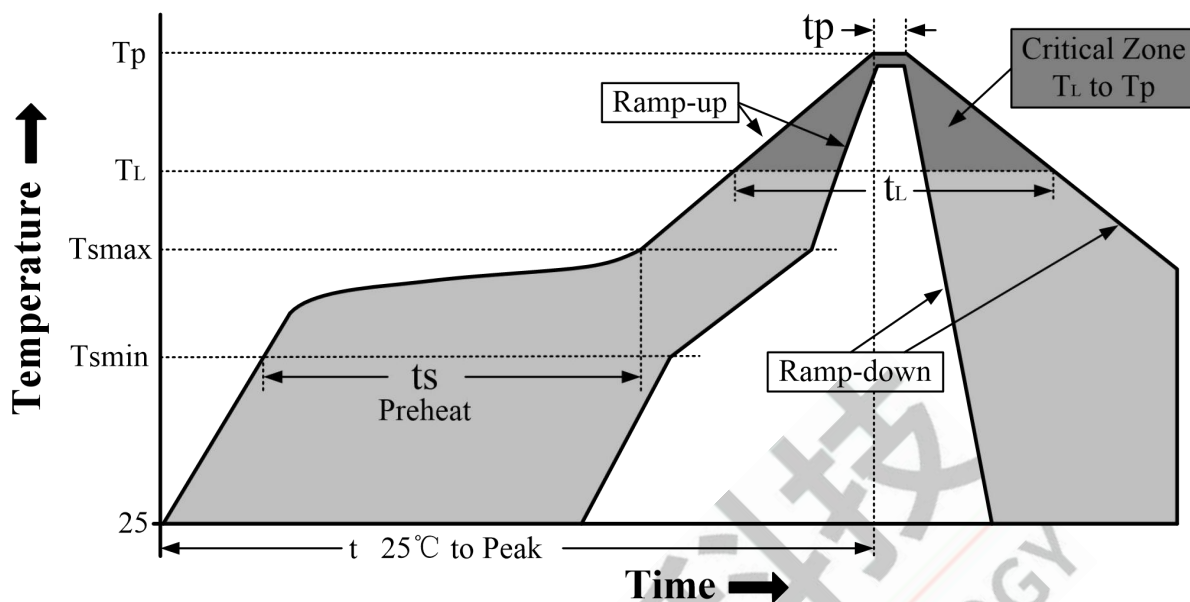


Figure 6-1 Classification Reflow Profile

Table 6-1 Classification Profiles

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak	Temperature Min (T_{smin})	100°C	150°C
	Temperature Max (T_{smax})	150°C	200°C
	Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-180 seconds
Average ramp-up rate (T_{smax} to T_p)		3°C/second max	3°C/second max
Liquidous temperature (T_L)		183°C	217°C
Time (t_L) maintained above T_L		60-150 seconds	60-150 seconds
Peak package body temperature (T_p)		See Table 6-2	See Table 6-3
Time within 5°C of actual Peak Temperature (t_p) ²		10-30 seconds	20-40 seconds
Ramp-down rate (T_p to T_L)		6°C/second max	6°C/second max
Time 25°C to peak temperature		6 minutes max	8 minutes max

Note

- 1.All temperatures refer to topside of the package, measured on the package body surface
- 2.Time within 5°C of actual peak temperature (t_p) specified for the reflow profiles is a "supplier" and "user" maximum.

Table 6-2 SnPb Classification Temperature

Package Thickness	Volume mm ³ < 350	Volume mm ³ ≥ 350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 6-3 Pb-free - Classification Temperature

Package Thickness	Volume mm ³ < 350	Volume mm ³ 350 - 2000	Volume mm ³ > 2000
< 1.6mm	260°C	260°C	260°C
1.6 mm - 2.5mm	260°C	250°C	245°C
> 2.5mm	250°C	245°C	245°C

Note

1.*Tolerance The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C.For example 260°C+0°C)at the rated MSL level.